

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
-- PATENT APPLICATION --

Applicant: : Aron T. Lunde
Application No.: : 10/053,963
Filed: : January 22, 2002
Title: : A DIE ASSEMBLY AND METHOD FOR FORMING A
DIE ON A WAFER
Examiner : Nguyen, Khiem D.
Group Art Unit : 2823
Confirmation No. : 5214
Attorney Docket No. : 37829.0400

RESPONSE TO OFFICE ACTION

Mail Stop AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Applicant hereby responds to the Office Action dated August 16, 2006, and respectfully requests the Examiner to consider the following remarks. Because this paper is being submitted within the three month shortened statutory period, no fee is believed to be due. However, Applicant respectfully requests and authorizes that any fees due or any overpayments be charged or credited to Deposit Account No. 19-2814.

Remarks/Arguments begin on page 2 of this paper.

Conclusion begins on page 7 of this paper.